

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	5	"5706578" or "6472293"	USPAT	2003/02/ 19 20:41
2	BRS	7	"5706578" or "6472293"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/ 19 20:55
3	BRS	102556	(semiconductor or die or chip or IC or integrat\$3 near circuit) and (pad or terminal or connector or contact) and wire	USPAT	2003/02/ 19 20:59
4	BRS	25202	(semiconductor or die or chip or IC or integrat\$3 near circuit) and (pad or terminal or connector or contact) with layers and wire	USPAT	2003/02/ 19 21:02
5	BRS	1607	257/786	USPAT	2003/02/ 20 14:08
6	BRS	69	257/786 and wire and solder and metal near layers with pad	USPAT	2003/02/ 19 21:34
7	BRS	79	257/786 and wire and metal near layers with pad not (257/786 and wire and solder and metal near layers with pad)	USPAT	2003/02/ 19 21:57
8	BRS	38	(semiconductor or IC or die or chip or Integrated near circuit) and bond near structure and wire and metal near layers with pad not (257/786 and wire and solder and metal near layers with pad)	USPAT; JPO	2003/02/ 20 13:02

	Type	Hits	Search Text	DBs	Time Stamp
9	BRS	44	(semiconductor or IC or die or chip or Integrated near circuit) and bond near structure and wire and metal near layers with pad	USPAT; JPO	2003/02/20 13:08
10	BRS	56	(semiconductor or IC or die or chip or Integrated near circuit) and bond near structure and wire and metal with layers with pad	USPAT; JPO	2003/02/20 13:22
11	BRS	98	(semiconductor or IC or die or chip or Integrated near circuit) and bond near structure and wire and metal same layers with (pad or terminal or connector or contact)	USPAT; JPO	2003/02/20 13:41
12	BRS	1	"5182420".PN.	USPAT	2003/02/20 13:37
13	BRS	1	"5367195".PN.	USPAT	2003/02/20 13:37
14	BRS	1	"5369220".PN.	USPAT	2003/02/20 13:37
15	BRS	1	"5734200".PN.	USPAT	2003/02/20 13:37
16	BRS	220	(semiconductor or IC or die or chip or Integrated near circuit) and bond near structure and wire and metal and (pad or terminal or connector or contact)	USPAT; JPO	2003/02/20 14:03

	Type	Hits	Search Text	DBs	Time Stamp
17	BRS	248	(semiconductor or IC or die or chip or Integrated near circuit) and bond near structure and wire and (pad or terminal or connector or contact)	USPAT; JPO	2003/02/20 14:06
18	BRS	994	257/786 and (pad or contact or terminal or connector) with (hole or open or opening or via)	USPAT	2003/02/24 14:12
19	BRS	1	"6020637".PN.	USPAT	2003/02/20 14:34
20	BRS	1	"6028358".PN.	USPAT	2003/02/20 14:34
21	BRS	1	"6046495".PN.	USPAT	2003/02/20 14:35
22	BRS	2935	(semiconductor or die or chip or IC or integrat\$3 near circuit) and (pad or contact or terminal or connector) with split	USPAT; JPO	2003/02/20 17:33
23	BRS	3582	(semiconductor or die or chip or IC) and (pad or contact or terminal or connector) with split\$4	USPAT; JPO	2003/02/20 19:21
24	BRS	228	(semiconductor or die or chip or IC) and (pad or contact or terminal or connector) with split\$4 with layers	USPAT; JPO	2003/02/20 17:35
25	BRS	216	(semiconductor or die or chip or IC) and (pad or contact or terminal or connector) with split\$4 same wire	USPAT; JPO	2003/02/20 19:31

	Type	Hits	Search Text	DBs	Time Stamp
26	BRS	258	(semiconductor or die or chip or IC) and (pad or contact or terminal or connector) with split\$4 same lead	USPAT; JPO	2003/02/20 19:39
27	BRS	315	(semiconductor or die or chip or IC) and split\$4 with (pad or contact or terminal or connector) and solder	USPAT; JPO	2003/02/20 19:48
28	BRS	615	(semiconductor or die or chip or IC) and (multi\$5 near layers) with (via or open or opening or hole) and solder and wire	USPAT	2003/02/20 20:51
29	BRS	342	(semiconductor or die or chip or IC) and metal same (multi\$5 near layers) with (via or open or opening or hole) and pad	USPAT	2003/02/21 14:31
30	BRS	14900	(semiconductor or die or chip or IC) and bond\$3 near pad	USPAT	2003/02/21 14:41
31	BRS	86	(semiconductor or die or chip or IC) and bond\$3 near pad same split\$4	USPAT	2003/02/21 14:32
32	BRS	6573	(semiconductor or die or chip or IC) and bond\$3 near pad and (metal or conductive or wire or wir\$3) near (layers or films)	USPAT	2003/02/21 14:43
33	BRS	6388	(semiconductor or die or chip or IC) and bond\$3 adj pad and (metal or conductive or wire or wir\$3) near (layers or films)	USPAT	2003/02/21 14:44

	Type	Hits	Search Text	DBs	Time Stamp
34	BRS	400	((semiconductor or die or chip or IC) and bond\$3 adj pad and (metal or conductive or wire or wir\$3) near (layers or films)) and 257/786	USPAT	2003/02/24 14:06
35	BRS	1	"5847466".PN.	USPAT	2003/02/21 14:54
36	BRS	1	"6100573".PN.	USPAT	2003/02/21 14:55
37	BRS	1	"6300688".PN.	USPAT	2003/02/21 14:55
38	BRS	0	"2001/0000928".PN.	USPAT	2003/02/21 14:55
39	BRS	1	"5394013".PN.	USPAT	2003/02/21 14:57
40	BRS	1	"5404047".PN.	USPAT	2003/02/21 14:57
41	BRS	1	"5463255".PN.	USPAT	2003/02/21 14:57
42	BRS	1	"5463255".PN.	USPAT	2003/02/21 14:58
43	BRS	1	"5502337".PN.	USPAT	2003/02/21 14:58
44	BRS	1	"5739587".PN.	USPAT	2003/02/21 14:58
45	BRS	1	"5751065".PN.	USPAT	2003/02/21 14:59
46	BRS	1	"5838043".PN.	USPAT	2003/02/21 14:59
47	BRS	1	"5869357".PN.	USPAT	2003/02/21 14:59
48	BRS	1	"5986343".PN.	USPAT	2003/02/21 15:00

	Type	Hits	Search Text	DBs	Time Stamp
49	BRS	1	"6043144".PN.	USPAT	2003/02/21 15:00
50	BRS	1	"6100573".PN.	USPAT	2003/02/21 15:00
51	BRS	1	"6163074".PN.	USPAT	2003/02/21 15:01
52	BRS	1	"6180993".PN.	USPAT	2003/02/21 15:01
53	BRS	1	"6180993".PN.	USPAT	2003/02/21 15:01
54	BRS	1	"6207547".PN.	USPAT	2003/02/21 15:01
55	BRS	1	"6222270".PN.	USPAT	2003/02/21 15:01
56	BRS	1	"6261944".PN.	USPAT	2003/02/21 15:02
57	BRS	1	"6291331".PN.	USPAT	2003/02/21 15:02
58	BRS	1	"6313537".PN.	USPAT	2003/02/21 15:02
59	BRS	1	"5036383".PN.	USPAT	2003/02/21 16:15
60	BRS	1	"5248903".PN.	USPAT	2003/02/21 16:16
61	BRS	1	"5502337".PN.	USPAT	2003/02/21 16:16
62	BRS	1	"5621246".PN.	USPAT	2003/02/21 16:16
63	BRS	1	"5736791".PN.	USPAT	2003/02/21 16:16
64	BRS	1	"5739587".PN.	USPAT	2003/02/21 16:17

	Type	Hits	Search Text	DBs	Time Stamp
65	BRS	1	"5923088".PN.	USPAT	2003/02/21 16:17
66	BRS	0	((semiconductor or die or chip or IC) and bond\$3 adj pad and spilt\$4 near (metal or conductive or wire or wir\$3) near (layers or films))	USPAT	2003/02/24 14:06
67	BRS	0	((semiconductor or die or chip or IC) and bond\$3 adj pad and spilt\$4 with (metal or conductive or wire or wir\$3) near (layers or films))	USPAT	2003/02/24 14:10
68	BRS	1	"6504252"	USPAT	2003/02/24 14:11
69	BRS	2	"6504252"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/24 14:11
70	BRS	1	"5084752".PN.	USPAT	2003/02/24 14:11
71	BRS	1	"6049135".PN.	USPAT	2003/02/24 14:11
72	BRS	1	"6136458".PN.	USPAT	2003/02/24 14:12
73	BRS	1607	257/786	USPAT	2003/02/24 16:36
74	BRS	1	"4551747".PN.	USPAT	2003/02/24 14:23
75	BRS	1	"5446311".PN.	USPAT	2003/02/24 14:24
76	BRS	1	"5592391".PN.	USPAT	2003/02/24 14:25
77	BRS	1	"5955789".PN.	USPAT	2003/02/24 14:25

	Type	Hits	Search Text	DBs	Time Stamp
78	BRS	1	"5986340".PN.	USPAT	2003/02/24 14:25
79	BRS	1	"6166403".PN.	USPAT	2003/02/24 14:26
80	BRS	1	"6181279".PN.	USPAT	2003/02/24 14:26
81	BRS	1	"6229404".PN.	USPAT	2003/02/24 14:27
82	BRS	1	"5430329".PN.	USPAT	2003/02/24 14:51
83	BRS	1	"5523626".PN.	USPAT	2003/02/24 14:52
84	BRS	1	"5847466".PN.	USPAT	2003/02/24 14:52
85	BRS	1	"5900668".PN.	USPAT	2003/02/24 14:53
86	BRS	1	"5903044".PN.	USPAT	2003/02/24 14:53
87	BRS	1	"5986299".PN.	USPAT	2003/02/24 14:54
88	BRS	1	"5986343".PN.	USPAT	2003/02/24 14:54
89	BRS	1	"6022791".PN.	USPAT	2003/02/24 14:55
90	BRS	1	"6031293".PN.	USPAT	2003/02/24 14:56
91	BRS	1	"6078100".PN.	USPAT	2003/02/24 14:56
92	BRS	1	"6090633".PN.	USPAT	2003/02/24 14:57
93	BRS	1	"5742009".PN.	USPAT	2003/02/24 15:00

	Type	Hits	Search Text	DBs	Time Stamp
94	BRS	1	"5075753".PN.	USPAT	2003/02/24 15:58
95	BRS	1	"5748550".PN.	USPAT	2003/02/24 15:58
96	BRS	2	"6018462"	USPAT	2003/02/24 16:38
97	BRS	1	"5519580".PN.	USPAT	2003/02/24 16:37
98	BRS	1	"6028366".PN.	USPAT	2003/02/24 16:37
99	BRS	1	"6225573".PN.	USPAT	2003/02/24 16:37
100	BRS	1	"6225573".PN.	USPAT	2003/02/24 16:37
101	BRS	1	"6246587".PN.	USPAT	2003/02/24 16:37
102	BRS	1	"6329605".PN.	USPAT	2003/02/24 16:38
103	BRS	2	"6090633"	USPAT	2003/02/24 16:57
104	BRS	1	"6078100".PN.	USPAT	2003/02/24 16:40
105	BRS	1	"5430329".PN.	USPAT	2003/02/24 16:42
106	BRS	1	"5523626".PN.	USPAT	2003/02/24 16:43
107	BRS	1	"5847466".PN.	USPAT	2003/02/24 16:43
108	BRS	1	"5900668".PN.	USPAT	2003/02/24 16:43
109	BRS	1	"5903044".PN.	USPAT	2003/02/24 16:43

	Type	Hits	Search Text	DBs	Time Stamp
110	BRS	1	"5986299".PN.	USPAT	2003/02/24 16:44
111	BRS	1	"5986343".PN.	USPAT	2003/02/24 16:56
112	BRS	1	"6022791".PN.	USPAT	2003/02/24 16:56
113	BRS	1	"6031293".PN.	USPAT	2003/02/24 16:57
114	BRS	1	"6078100".PN.	USPAT	2003/02/24 16:57
115	BRS	4	"6022791"	USPAT	2003/02/24 16:59
116	BRS	4	"6166403"	USPAT	2003/02/24 17:00
117	BRS	873	438/612 not 257/786	USPAT	2003/02/24 17:48
118	BRS	1	"5134460".PN.	USPAT	2003/02/24 17:07
119	BRS	1	"5731624".PN.	USPAT	2003/02/24 17:07
120	BRS	1	"5795819".PN.	USPAT	2003/02/24 17:07
121	BRS	1	"5864946".PN.	USPAT	2003/02/24 17:07
122	BRS	1	"6133136".PN.	USPAT	2003/02/24 17:07
123	BRS	1	"6187680".PN.	USPAT	2003/02/24 17:07
124	BRS	1	"5093279".PN.	USPAT	2003/02/24 17:39
125	BRS	1	"5244837".PN.	USPAT	2003/02/24 17:39

	Type	Hits	Search Text	DBs	Time Stamp
126	BRS	1	"5436412".PN.	USPAT	2003/02/24 17:39
127	BRS	1	"5438166".PN.	USPAT	2003/02/24 17:40
128	BRS	27	"5883435"	USPAT	2003/02/24 17:48
129	BRS	1	"6504252"	USPAT	2003/02/25 14:33
130	BRS	27	"5883435"	USPAT	2003/02/25 16:46
131	BRS	1	6455943.pn.	USPAT	2003/02/25 16:47
132	BRS	0	070312478.pn.	USPAT; JPO	2003/02/25 19:19
133	BRS	0	70312478.pn.	USPAT; JPO	2003/02/25 19:19
134	BRS	0	700312478.pn.	USPAT; JPO	2003/02/25 19:19
135	BRS	0	0070312478.pn.	USPAT; JPO	2003/02/25 19:19
136	BRS	0	0070312478.pn.	JPO	2003/02/25 19:19
137	BRS	0	070312478.pn.	JPO	2003/02/25 19:19
138	BRS	0	"070312478"	JPO	2003/02/25 19:19
139	BRS	1	07312478.pn.	JPO	2003/02/25 19:20
140	BRS	1	07312478.pn.	USPAT; JPO	2003/02/25 19:20

	Type	Hits	Search Text	DBs	Time Stamp
141	BRS	12	07312478.pn. or 6018462.pn. or 3772575.pn. or 6300688.pn. or 6465892.pn. or 5706578.pn. or 5854513.pn. or 6504252.pn. or 6078100.pn. or 6509643.pn. or 6455943.pn. or 5883435.pn.	USPAT; JPO	2003/02/ 25 19:22
142	BRS	1701	257/786 or 438/612	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/ 25 20:20
143	BRS	1962	257/784	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/ 25 20:21